



Solder plus Support

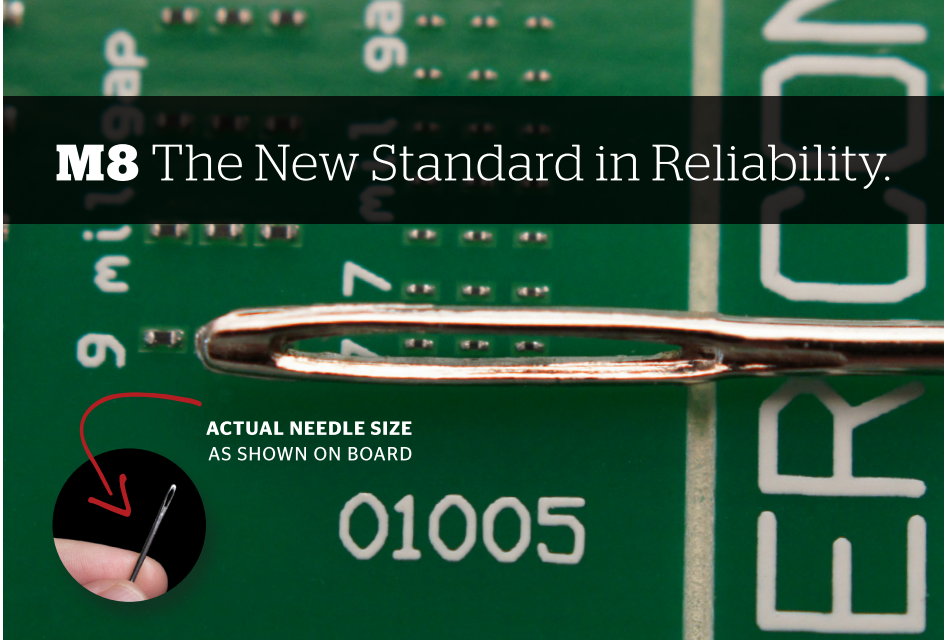
M8

SOLDER PASTE



M8 SOLDER PASTE AT A GLANCE

- ▶ Halogen-free
- ▶ Low voiding on BGA and BTC components
- ▶ REACH and RoHS compliant
- ▶ Consistent print volume on area ratios > 0.5
- ▶ High SIR/Electrically safe residue
- ▶ Compatible with conformal coating
- ▶ Mitigates head-in-pillow



AIM, a leading global manufacturer of solder assembly materials for the electronics industry, introduces M8 Solder Paste, a high reliability no clean paste for use with SAC305 and Sn/Pb alloys.

M8 NO CLEAN SOLDER PASTE is engineered for the most demanding electronic assembly applications including automotive, LED lighting, EMS or military applications. M8 addresses the challenges facing today's PCB assembler, including ultra-fine pitch printing, HiP BGA defects and voiding on LED and QFN components. M8's innovative activation system provides powerful, durable wetting to all plating finishes without compromising print performance. M8 does not require refrigeration for up to three months and provides consistent repeatable print results even after long abandon times. M8's post soldering residue are minimal, clear and pin-probeable with extraordinarily high SIR properties. Industry collaborative testing has demonstrated M8 residues can be coated without removal or easily removed with readily available chemistry.

M8 No Clean Solder Paste - Powerful, Reliable, Adaptable. Ask how to get your sample today.

